



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BSC005N03LS5	<b>Issued</b>	26. June 2021
<b>MA#</b>	MA005566228		
<b>Package</b>	PG-TDSON-8-27	<b>Weight*</b>	124.89 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.940	1.55	1.55	15531	15531
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		124	
	non noble metal	iron	7439-89-6	0.052	0.04		415	
	non noble metal	copper	7440-50-8	51.740	41.44	41.49	414276	414815
wire	noble metal	gold	7440-57-5	0.031	0.02	0.02	246	246
encapsulation	organic material	carbon black	1333-86-4	0.075	0.06		599	
	plastics	epoxy resin	-	5.912	4.73		47337	
	inorganic material	silicondioxide	60676-86-0	31.432	25.17	29.96	251666	299602
leadfinish	non noble metal	tin	7440-31-5	1.392	1.11	1.11	11142	11142
plating	noble metal	silver	7440-22-4	0.194	0.16	0.16	1552	1552
solder	non noble metal	tin	7440-31-5	0.050	0.04		404	
	noble metal	silver	7440-22-4	0.063	0.05		505	
	non noble metal	lead	7439-92-1	2.409	1.93	2.02	19288	20197
heat sink clip	inorganic material	phosphorus	7723-14-0	0.009	0.01		71	
	non noble metal	iron	7439-89-6	0.030	0.02		237	
	non noble metal	copper	7440-50-8	29.551	23.66	23.69	236607	236915
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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